# E·XFL

## Intel - 5SGXEA5H1F35C2LN Datasheet



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#### Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Detuns	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	552
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea5h1f35c2ln

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Symbol	Description	Condition	Min <sup>(4)</sup>	Тур	Max <sup>(4)</sup>	Unit
+	Power supply ramp time	Standard POR	200 µs	_	100 ms	—
t <sub>ramp</sub>	Power supply ramp time	Fast POR	200 µs		4 ms	_

### Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

### Notes to Table 6:

(1)  $V_{CCPD}$  must be 2.5 V when  $V_{CCI0}$  is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V.  $V_{CCPD}$  must be 3.0 V when  $V_{CCI0}$  is 3.0 V.

(2) If you do not use the design security feature in Stratix V devices, connect V<sub>CCBAT</sub> to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V<sub>CCBAT</sub>. Stratix V devices will not exit POR if V<sub>CCBAT</sub> stays at logic low.

(3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.

(4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

## Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit	
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V	
(1), (3)	side)	un, uo, ui	2.375	2.5	2.625	v	
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V	
(1), (3)	side)	ux, us	2.375	2.5	2.625	v	
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V	
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V <sub>CCHSSI_R</sub> T	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
			0.82	0.85	0.88		
V <sub>CCR_GXBL</sub>	Pacaivar analog powar supply (left side)		0.87	0.90	0.93	v	
(2)	Receiver analog power supply (left side)	GX, GS, GT	0.97	1.0	1.03	v	
			1.03	1.05	1.07		

Table 8 shows the transceiver power supply voltage requirements for various conditions.

**Table 8. Transceiver Power Supply Voltage Requirements** 

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB <sup>(2)</sup>	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true:	All	1.05			
<ul> <li>Data rate &gt; 10.3 Gbps.</li> <li>DFE is used.</li> </ul>	All	1.05			
If ANY of the following conditions are true <sup>(1)</sup> :			3.0		
ATX PLL is used.					
■ Data rate > 6.5Gbps.	All	1.0			
■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.				1.5	V
If ALL of the following	C1, C2, I2, and I3YY	0.90	2.5		
<ul><li>conditions are true:</li><li>ATX PLL is not used.</li></ul>					
■ Data rate ≤ 6.5Gbps.	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		
<ul> <li>DFE, AEQ, and EyeQ are not used.</li> </ul>					

## Notes to Table 8:

(1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.

(2) If the VCCR\_GXB and VCCT\_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR\_GXB and VCCT\_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

## **DC Characteristics**

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

### **Supply Current**

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

1/0 Stondard		V <sub>ccio</sub> (V)			V <sub>REF</sub> (V)			V <sub>TT</sub> (V)	
I/O Standard	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	V <sub>REF</sub> – 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V <sub>REF</sub> – 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCI0</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCI0</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCI0</sub>	0.49 * V <sub>CCI0</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCI0</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	_	V <sub>CCI0</sub> /2	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	_	V <sub>CCI0</sub> /2	_
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.53 * V <sub>CCIO</sub>	—	V <sub>CCI0</sub> /2	
HSUL-12	1.14	1.2	1.3	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	_	_	_

Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Device	es
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Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices	(Part 1 of 2)
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I/O Standard	V <sub>IL(D(</sub>	<sub>:)</sub> (V)	V <sub>IH(D</sub>	<sub>C)</sub> (V)	V <sub>IL(AC)</sub> (V)	V <sub>IH(AC)</sub> (V)	V <sub>ol</sub> (V)	V <sub>oh</sub> (V)	L (mA)	I <sub>oh</sub>	
ijo Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	I <sub>ol</sub> (mA)	(mA)	
SSTL-2 Class I	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCI0</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.608	V <sub>TT</sub> + 0.608	8.1	-8.1	
SSTL-2 Class II	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCI0</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.81	V <sub>TT</sub> + 0.81	16.2	-16.2	
SSTL-18 Class I	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCI0</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	V <sub>TT</sub> – 0.603	V <sub>TT</sub> + 0.603	6.7	-6.7	
SSTL-18 Class II	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCI0</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	0.28	V <sub>CCI0</sub> – 0.28	13.4	-13.4	
SSTL-15 Class I		V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCI0</sub>	0.8 * V <sub>CCI0</sub>	8	-8	
SSTL-15 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCI0</sub>	0.8 * V <sub>CCI0</sub>	16	-16	
SSTL-135 Class I, II		V <sub>REF</sub> – 0.09	V <sub>REF</sub> + 0.09	_	V <sub>REF</sub> – 0.16	V <sub>REF</sub> + 0.16	0.2 * V <sub>CCI0</sub>	0.8 * V <sub>CCI0</sub>	_	_	
SSTL-125 Class I, II		V <sub>REF</sub> – 0.85	V <sub>REF</sub> + 0.85	_	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCI0</sub>	0.8 * V <sub>CCI0</sub>	_	_	
SSTL-12 Class I, II		V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1		V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>		_	

I/O Standard	V <sub>IL(DI</sub>	<sub>c)</sub> (V)	V <sub>IH(D</sub>	<sub>C)</sub> (V)	V <sub>IL(AC)</sub> (V)	V <sub>IH(AC)</sub> (V)	V <sub>ol</sub> (V)	V <sub>oh</sub> (V)	I (mA)	I <sub>oh</sub>
i/U Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	l <sub>oi</sub> (mA)	(mA)
HSTL-18 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	$V_{REF} - 0.2$	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	8	-8
HSTL-18 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	16	-16
HSTL-15 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	8	-8
HSTL-15 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	16	-16
HSTL-12 Class I	-0.15	V <sub>REF</sub> – 0.08	V <sub>REF</sub> + 0.08	V <sub>CCIO</sub> + 0.15	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.25* V <sub>CCI0</sub>	0.75* V <sub>CCI0</sub>	8	-8
HSTL-12 Class II	-0.15	V <sub>REF</sub> – 0.08	V <sub>REF</sub> + 0.08	V <sub>CCIO</sub> + 0.15	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.25* V <sub>CCIO</sub>	0.75* V <sub>CCI0</sub>	16	-16
HSUL-12	_	V <sub>REF</sub> – 0.13	V <sub>REF</sub> + 0.13	_	V <sub>REF</sub> – 0.22	V <sub>REF</sub> + 0.22	0.1* V <sub>CCIO</sub>	0.9* V <sub>CCI0</sub>	_	_

## Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)

Table 20. Differential SSTL I/O Standards for Stratix V Devices

I/O Standard		V <sub>ccio</sub> (V)		V <sub>SWIN</sub>	<sub>G(DC)</sub> (V)		V <sub>X(AC)</sub> (V)		V <sub>swing(</sub> ,	<sub>AC)</sub> (V)
ijo Stanuaru	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V <sub>CCI0</sub> + 0.6	V <sub>CCI0</sub> /2- 0.2	_	V <sub>CCI0</sub> /2 + 0.2	0.62	V <sub>CCI0</sub> + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V <sub>CCI0</sub> + 0.6	V <sub>CCI0</sub> /2- 0.175	_	V <sub>CCI0</sub> /2 + 0.175	0.5	V <sub>CCI0</sub> + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(1)	V <sub>CCI0</sub> /2- 0.15	_	V <sub>CCI0</sub> /2 + 0.15	0.35	_
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(1)	V <sub>CCI0</sub> /2- 0.15	V <sub>CCI0</sub> /2	V <sub>CCI0</sub> /2 + 0.15	2(V <sub>IH(AC)</sub> - V <sub>REF</sub> )	2(V <sub>IL(AC)</sub> - V <sub>REF</sub> )
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(1)	V <sub>CCI0</sub> /2- 0.15	V <sub>CCI0</sub> /2	V <sub>CCI0</sub> /2 + 0.15	2(V <sub>IH(AC)</sub> - V <sub>REF</sub> )	_
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	_	V <sub>REF</sub> -0.15	V <sub>CCI0</sub> /2	V <sub>REF</sub> + 0.15	-0.30	0.30

Note to Table 20:

(1) The maximum value for  $V_{SWING(DC)}$  is not defined. However, each single-ended signal needs to be within the respective single-ended limits  $(V_{IH(DC)} \text{ and } V_{IL(DC)})$ .

I/O	I/O V <sub>ccio</sub> (V)		V <sub>DIF(I</sub>	<sub>DC)</sub> (V)	V <sub>X(AC)</sub> (V)				V <sub>CM(DC)</sub> (V	V <sub>DIF(AC)</sub> (V)			
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	_	0.78	_	1.12	0.78	_	1.12	0.4	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	_	0.68	_	0.9	0.68	_	0.9	0.4	_

Symbol/ Description	Conditions	Transceiver Speed Grade 1		Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t <sub>pll_lock</sub> (16)	_			10		—	10			10	μs

#### Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 7 of 7)

#### Notes to Table 23:

(2) The reference clock common mode voltage is equal to the V<sub>CCR\_GXB</sub> power supply level.

(3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.

- (4) This supply follows VCCR\_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t<sub>LTR</sub> is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t<sub>LTD</sub> is time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high.
- (13) t<sub>LTD\_manual</sub> is the time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14)  $t_{LTR\_LTD\_manual}$  is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx\_is\_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15)  $t_{pll_powerdown}$  is the PLL powerdown minimum pulse width.
- (16) t<sub>pll lock</sub> is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage  $V_{ID}$  after device configuration is equal to 4 × (absolute  $V_{MAX}$  for receiver pin  $V_{ICM}$ ).
- (19) For ES devices,  $R_{BEF}$  is 2000  $\Omega \pm 1\%$ .
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20\*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

<sup>(1)</sup> Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Stratix V Device Overview.





Figure 3 shows the Stratix V AC gain curves for GX channels.

Figure 3. AC Gain Curves for GX Channels (full bandwidth)

Stratix V GT devices contain both GX and GT channels. All transceiver specifications for the GX channels not listed in Table 28 are the same as those listed in Table 23.

Table 28 lists the Stratix V GT transceiver specifications.

Symbol/	Conditions	:	Transceive Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Reference Clock								
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	/IL, 1.4-V PC	ML, 1.5-V P	CML, 2.5-V and HCSL	PCML, Diffe	rential LVPE	ECL, LVDS
	RX reference clock pin		1.4-V PCML	., 1.5-V PCN	IL, 2.5-V PC	ML, LVPEC	L, and LVDS	6
Input Reference Clock Frequency (CMU PLL) <sup>(6)</sup>	_	40	_	710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) <sup>(6)</sup>	_	100	-	710	100	_	710	MHz
Rise time	20% to 80%		_	400		—	400	
Fall time	80% to 20%			400	—		400	ps
Duty cycle	—	45		55	45		55	%
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz
Spread-spectrum downspread	PCle	_	0 to -0.5		_	0 to -0.5	_	%
On-chip termination resistors <sup>(19)</sup>	_	_	100	_	_	100	_	Ω
Absolute V <sub>MAX</sub> <sup>(3)</sup>	Dedicated reference clock pin		_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_	_	1.2	
Absolute V <sub>MIN</sub>	—	-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	_	200		1600	200	_	1600	mV
V <sub>ICM</sub> (AC coupled)	Dedicated reference clock pin		1050/1000 (	2)		1050/1000 (	2)	mV
	RX reference clock pin	1	.0/0.9/0.85 (	22)	1	.0/0.9/0.85 (	22)	V
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV

## Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) <sup>(1)</sup>

Symbol/	Conditions	5	Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors <sup>(7)</sup>	GT channels		100	_	_	100	_	Ω
	85- $\Omega$ setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
for GX channels <sup>(19)</sup>	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting		150 ± 30%	_	_	150 ± 30%	_	Ω
V <sub>ICM</sub> (AC coupled)	GT channels		650		—	650	—	mV
	VCCR_GXB = 0.85 V or 0.9 V		600	_	_	600		mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth		700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth		750	_	_	750	_	mV
t <sub>LTR</sub> <sup>(9)</sup>	—	—	—	10	—	—	10	μs
t <sub>LTD</sub> <sup>(10)</sup>		4			4			μs
t <sub>LTD_manual</sub> <sup>(11)</sup>	—	4	—	—	4	—	_	μs
t <sub>LTR_LTD_manual</sub> <sup>(12)</sup>	_	15			15	—		μs
Run Length	GT channels	_	_	72	—	—	72	CID
nun Lengin	GX channels				(8)			
CDR PPM	GT channels			1000	_	—	1000	± PPM
	GX channels				(8)			
Programmable	GT channels	_	_	14	—	—	14	dB
equalization (AC Gain) <sup>(5)</sup>	GX channels				(8)			
Programmable	GT channels	_	—	7.5	—	—	7.5	dB
DC gain <sup>(6)</sup>	GX channels				(8)			
Differential on-chip termination resistors <sup>(7)</sup>	GT channels	_	100	_	_	100	_	Ω
Transmitter	·1							
Supported I/O Standards	_			1.4-V	and 1.5-V F	PCML		
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600		12,500	600	_	12,500	Mbps

## Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5)<sup>(1)</sup>

## **PLL Specifications**

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to  $85^{\circ}$ C) and the industrial junction temperature range (-40° to  $100^{\circ}$ C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f <sub>IN</sub>	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 <sup>(1)</sup>	MHz
f <sub>INPFD</sub>	Input frequency to the PFD	5	—	325	MHz
f <sub>finpfd</sub>	Fractional Input clock frequency to the PFD	50	—	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f <sub>VCO</sub>	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
t <sub>einduty</sub>	Input clock or external feedback clock input duty cycle	40		60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	_	717 <sup>(2)</sup>	MHz
f <sub>out</sub>	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f <sub>out_ext</sub>	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 <sup>(2)</sup>	MHz
t <sub>outduty</sub>	Duty cycle for a dedicated external clock output (when set to <b>50%</b> )	45	50	55	%
t <sub>FCOMP</sub>	External feedback clock compensation time	_	—	10	ns
f <sub>dyconfigclk</sub>	Dynamic Configuration Clock used for <code>mgmt_clk</code> and <code>scanclk</code>	_	_	100	MHz
t <sub>LOCK</sub>	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
t <sub>olock</sub>	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3	—	MHz
f <sub>CLBW</sub>	PLL closed-loop medium bandwidth	_	1.5		MHz
	PLL closed-loop high bandwidth (7)		4	—	MHz
t <sub>PLL_PSERR</sub>	Accuracy of PLL phase shift			±50	ps
t <sub>areset</sub>	Minimum pulse width on the areset signal	10	_		ns

Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit		
		Modes us	ing Three	DSPs						
One complex 18 x 25	425	425	415	340	340	275	265	MHz		
Modes using Four DSPs										
One complex 27 x 27	465	465	465	380	380	300	290	MHz		

## Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

## **Memory Block Specifications**

Table 33 lists the Stratix V memory block specifications.

## Table 33. Memory Block Performance Specifications for Stratix V Devices <sup>(1), (2)</sup> (Part 1 of 2)

		<b>Resources Used</b>		Performance							
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
IVILAD	Simple dual-port, x16 depth <sup>(3)</sup>	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

0b.al	Oanditiana		C1		C2,	C2L, I	2, I2L	C3,	13, 131	., <b>I</b> 3YY		C4,I	4	11 14
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter				<u>.</u>						<u>.</u>				
	SERDES factor J = 3 to 10 <sup>(9)</sup> , <sup>(11)</sup> , <sup>(12)</sup> , <sup>(13)</sup> , <sup>(14)</sup> , <sup>(15)</sup> , <sup>(16)</sup>	(6)		1600	(6)		1434	(6)		1250	(6)		1050	Mbps
	SERDES factor J $\geq 4$													
True Differential I/O Standards	LVDS TX with DPA <sup>(12)</sup> , <sup>(14)</sup> , <sup>(15)</sup> , <sup>(16)</sup>	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)	_	1250	Mbps
- f <sub>HSDR</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f <sub>HSDR</sub> (data rate) <sup>(10)</sup>	SERDES factor J = 4 to 10 $(17)$	(6)		1100	(6)		1100	(6)		840	(6)		840	Mbps
t <sub>x Jitter</sub> - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_		160	_	_	160			160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t <sub>x Jitter</sub> - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_		300	_		300	_	_	300	_		325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_		0.2			0.2			0.2	_		0.25	UI

## Table 36. High-Speed I/O Specifications for Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 4)

Jitter Fre	quency (Hz)	Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Table 38.	LVDS Soft-CDR/D	PA Sinusoidal	<b>Jitter Mask Valu</b>	es for a Data Ra	te > 1.25 Gbps
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Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.





## **DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications**

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices (1)

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

#### Note to Table 39:

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices <sup>(1), (2)</sup> (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

Clock Network	Parameter S	Symbol	C	C1 C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,14		Unit	
NELWURK		-	Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	$t_{JIT(per)}$	-25	25	-25	25	-30	30	-35	35	ps
PHY Clock	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{\text{JIT}(\text{duty})}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

## Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 2 of 2) (2), (3)

## Notes to Table 42:

(1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.

(2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.

(3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

## **OCT Calibration Block Specifications**

Table 43 lists the OCT calibration block specifications for Stratix V devices.

## Table 43. OCT Calibration Block Specifications for Stratix V Devices

Symbol	Description	Min	Тур	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks		_	20	MHz
T <sub>OCTCAL</sub>	Number of OCTUSRCLK clock cycles required for OCT $\rm R_S/R_T$ calibration	_	1000	_	Cycles
T <sub>OCTSHIFT</sub>	Number of OCTUSRCLK clock cycles required for the OCT code to shift out	—	32	_	Cycles
T <sub>RS_RT</sub>	Time required between the dyn_term_ctrl and oe signal transitions in a bidirectional I/O buffer to dynamically switch between OCT $R_S$ and $R_T$ (Figure 10)	_	2.5		ns

Figure 10 shows the timing diagram for the oe and dyn\_term\_ctrl signals.

### Figure 10. Timing Diagram for oe and dyn\_term\_ctrl Signals



Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) <sup>(4), (5)</sup>
Stratix V E <sup>(1)</sup>	5SEE9	—	342,742,976	700,888
	5SEEB	_	342,742,976	700,888

### Table 47. Uncompressed .rbf Sizes for Stratix V Devices

### Notes to Table 47:

(1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.

(2) 36-transceiver devices.

(3) 24-transceiver devices.

(4) File size for the periphery image.

(5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

• For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help.* 

Table 48 lists the minimum configuration time estimates for Stratix V devices.

Variant	Mambar		Active Serial <sup>(1)</sup>		Fast Passive Parallel <sup>(2)</sup>			
	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	A3	4	100	0.534	32	100	0.067	
	AS	4	100	0.344	32	100	0.043	
	A4	4	100	0.534	32	100	0.067	
	A5	4	100	0.675	32	100	0.084	
	A7	4	100	0.675	32	100	0.084	
GX	A9	4	100	0.857	32	100	0.107	
	AB	4	100	0.857	32	100	0.107	
	B5	4	100	0.676	32	100	0.085	
	B6	4	100	0.676	32	100	0.085	
	B9	4	100	0.857	32	100	0.107	
	BB	4	100	0.857	32	100	0.107	
ст	C5	4	100	0.675	32	100	0.084	
GT	C7	4	100	0.675	32	100	0.084	

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is more than 1.

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nCONFIG low to CONF_DONE low	—	600	ns
t <sub>CF2ST0</sub>	nCONFIG low to nSTATUS low	—	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	_	μS
t <sub>STATUS</sub>	nSTATUS low pulse width	268	1,506 <sup>(2)</sup>	μS
t <sub>CF2ST1</sub>	nCONFIG high to nSTATUS high	—	1,506 <sup>(2)</sup>	μS
t <sub>CF2CK</sub> <sup>(5)</sup>	nCONFIG high to first rising edge on DCLK	1,506	_	μS
t <sub>ST2CK</sub> <sup>(5)</sup>	nSTATUS high to first rising edge of DCLK	2	—	μS
t <sub>DSU</sub>	DATA [] setup time before rising edge on DCLK	5.5		ns
t <sub>DH</sub>	DATA [] hold time after rising edge on DCLK	N-1/f <sub>DCLK</sub> <sup>(5)</sup>		S
t <sub>CH</sub>	DCLK high time	$0.45  imes 1/f_{MAX}$		S
t <sub>CL</sub>	DCLK low time	$0.45\times1/f_{MAX}$		S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>		S
f	DCLK frequency (FPP ×8/×16)	—	125	MHz
f <sub>MAX</sub>	DCLK frequency (FPP ×32)	—	100	MHz
t <sub>R</sub>	Input rise time	—	40	ns
t <sub>F</sub>	Input fall time	—	40	ns
t <sub>CD2UM</sub>	CONF_DONE high to user mode <sup>(3)</sup>	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU}$ + (8576 × CLKUSR period) <sup>(4)</sup>	_	_

#### Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the  ${\tt DCLK}\mbox{-to-DATA}$  ratio and  $f_{{\tt DCLK}}$  is the  ${\tt DCLK}$  frequency the system is operating.
- (6) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

## **Active Serial Configuration Timing**

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52.	DCLK Frequency	Specification in the <i>l</i>	AS Configuration Scheme	(1), (2)
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Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

#### Notes to Table 52:

(1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.

(2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.





#### Notes to Figure 14:

- (1) If you are using AS  $\times 4$  mode, this signal represents the AS\_DATA[3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or CLKUSR pin.
- (3) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

Table 53 lists the timing parameters for AS  $\times 1$  and AS  $\times 4$  configurations in Stratix V devices.

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CO</sub>	DCLK falling edge to AS_DATA0/ASDO output	—	2	ns
t <sub>SU</sub>	Data setup time before falling edge on DCLK	1.5	—	ns
t <sub>H</sub>	Data hold time after falling edge on DCLK	0	—	ns

	Available	Min	Fast	Model	Slow Model							
	Settings	<b>Offset</b> (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

#### Notes to Table 58:

(1) You can set this value in the Quartus II software by selecting D1, D2, D3, D5, and D6 in the Assignment Name column of Assignment Editor.

(2) Minimum offset does not include the intrinsic delay.

## **Programmable Output Buffer Delay**

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

Table 59. Programmable Output Buffer Delay for Stratix V Devices (	Table 59.	Programmable Out	put Buffer Delay	y for Stratix V Devices (
--	-----------	------------------	------------------	---------------------------

Symbol	Parameter	Typical	Unit
		0 (default)	ps
D <sub>outbuf</sub>	Rising and/or falling edge delay	25	ps
		50	ps
		75	ps

Note to Table 59:

(1) You can set the programmable output buffer delay in the Quartus II software by setting the Output Buffer Delay Control assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the Output Buffer Delay assignment.

## Glossary

Table 60 lists the glossary for this chapter.

Table 60. Glossary (Part 1 of 4)

Letter	Subject	Definitions
Α		
В	—	—
С		
D	_	_
E	—	_
	f <sub>HSCLK</sub>	Left and right PLL input clock frequency.
F	f <sub>HSDR</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDR</sub> = 1/TUI), non-DPA.
	f <sub>hsdrdpa</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDRDPA</sub> = 1/TUI), DPA.

## Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G		
Н	_	_
Ι		
J	J JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS TDI $t_{JCP}$ $t_{JCP}$ $t_{JPCO}$ $t_{JPCO}$ $t_{JPXZ}$ TDO $t_{JPXZ}$ $t_{JPXZ}$
K L M N O	_	_
Ρ	PLL Specifications	Diagram of PLL Specifications (1)
Q		_
	1	

## **Document Revision History**

Table 61 lists the revision history for this chapter.

 Table 61. Document Revision History (Part 1 of 3)

Date	Version	Changes	
June 2018	3.9	<ul> <li>Added the "Stratix V Device Overshoot Duration" figure.</li> </ul>	
		<ul> <li>Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.</li> </ul>	
		<ul> <li>Changed the minimum value for t<sub>CD2UMC</sub> in the "PS Timing Parameters for Stratix V Devices" table.</li> </ul>	
		<ul> <li>Changed the condition for 100-Ω R<sub>D</sub> in the "OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices" table.</li> </ul>	
April 2017	3.8	<ul> <li>Changed the minimum value for t<sub>CD2UMC</sub> in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table</li> </ul>	
		<ul> <li>Changed the minimum value for t<sub>CD2UMC</sub> in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is &gt;1" table.</li> </ul>	
		<ul> <li>Changed the minimum value for t<sub>CD2UMC</sub> in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is &gt;1" table.</li> </ul>	
		<ul> <li>Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency" table.</li> </ul>	
	3.7	<ul> <li>Added the V<sub>ID</sub> minimum specification for LVPECL in the "Differential I/O Standard Specifications for Stratix V Devices" table</li> </ul>	
June 2016		<ul> <li>Added the I<sub>OUT</sub> specification to the "Absolute Maximum Ratings for Stratix V Devices" table.</li> </ul>	
December 2015	3.6	Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.	
December 2015	3.5	<ul> <li>Changed the transmitter, receiver, and ATX PLL data rate specifications in the "Transceiver Specifications for Stratix V GX and GS Devices" table.</li> </ul>	
December 2015	0 3.0	<ul> <li>Changed the configuration .rbf sizes in the "Uncompressed .rbf Sizes for Stratix V Devices" table.</li> </ul>	
		• Changed the data rate specification for transceiver speed grade 3 in the following tables:	
		<ul> <li>"Transceiver Specifications for Stratix V GX and GS Devices"</li> </ul>	
		<ul> <li>"Stratix V Standard PCS Approximate Maximum Date Rate"</li> </ul>	
		<ul> <li>"Stratix V 10G PCS Approximate Maximum Data Rate"</li> </ul>	
July 2015	3.4	<ul> <li>Changed the conditions for reference clock rise and fall time, and added a note to the "Transceiver Specifications for Stratix V GX and GS Devices" table.</li> </ul>	
		<ul> <li>Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Transceiver Specifications for Stratix V GX and GS Devices" table.</li> </ul>	
		<ul> <li>Changed the t<sub>co</sub> maximum value in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table.</li> </ul>	
		<ul> <li>Removed the CDR ppm tolerance specification from the "Transceiver Specifications for Stratix V GX and GS Devices" table.</li> </ul>	

## Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes
		Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.
		<ul> <li>Added the I3YY speed grade to the V<sub>CC</sub> description in Table 6.</li> </ul>
		<ul> <li>Added the I3YY speed grade to V<sub>CCHIP_L</sub>, V<sub>CCHIP_R</sub>, V<sub>CCHSSI_L</sub>, and V<sub>CCHSSI_R</sub> descriptions in Table 7.</li> </ul>
		■ Added 240-Ω to Table 11.
		Changed CDR PPM tolerance in Table 23.
		<ul> <li>Added additional max data rate for fPLL in Table 23.</li> </ul>
		<ul> <li>Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25.</li> </ul>
		<ul> <li>Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26.</li> </ul>
		Changed CDR PPM tolerance in Table 28.
		<ul> <li>Added additional max data rate for fPLL in Table 28.</li> </ul>
		Changed the mode descriptions for MLAB and M20K in Table 33.
		■ Changed the Max value of f <sub>HSCLK_OUT</sub> for the C2, C2L, I2, I2L speed grades in Table 36.
November 2014	3.3	<ul> <li>Changed the frequency ranges for C1 and C2 in Table 39.</li> </ul>
		Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.
		<ul> <li>Added note about nSTATUS to Table 50, Table 51, Table 54.</li> </ul>
		<ul> <li>Changed the available settings in Table 58.</li> </ul>
		<ul> <li>Changed the note in "Periphery Performance".</li> </ul>
		<ul> <li>Updated the "I/O Standard Specifications" section.</li> </ul>
		<ul> <li>Updated the "Raw Binary File Size" section.</li> </ul>
		<ul> <li>Updated the receiver voltage input range in Table 22.</li> </ul>
		<ul> <li>Updated the max frequency for the LVDS clock network in Table 36.</li> </ul>
		■ Updated the DCLK note to Figure 11.
		<ul> <li>Updated Table 23 VO<sub>CM</sub> (DC Coupled) condition.</li> </ul>
		<ul> <li>Updated Table 6 and Table 7.</li> </ul>
		■ Added the DCLK specification to Table 55.
		<ul> <li>Updated the notes for Table 47.</li> </ul>
		<ul> <li>Updated the list of parameters for Table 56.</li> </ul>
November 2013	3.2	Updated Table 28
November 2013	3.1	Updated Table 33
November 2013	3.0	Updated Table 23 and Table 28
October 2013	2.9	<ul> <li>Updated the "Transceiver Characterization" section</li> </ul>
		<ul> <li>Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59</li> </ul>
October 2013	2.8	<ul> <li>Added Figure 1 and Figure 3</li> </ul>
		<ul> <li>Added the "Transceiver Characterization" section</li> </ul>
		<ul> <li>Removed all "Preliminary" designations.</li> </ul>